

leti
cea tech

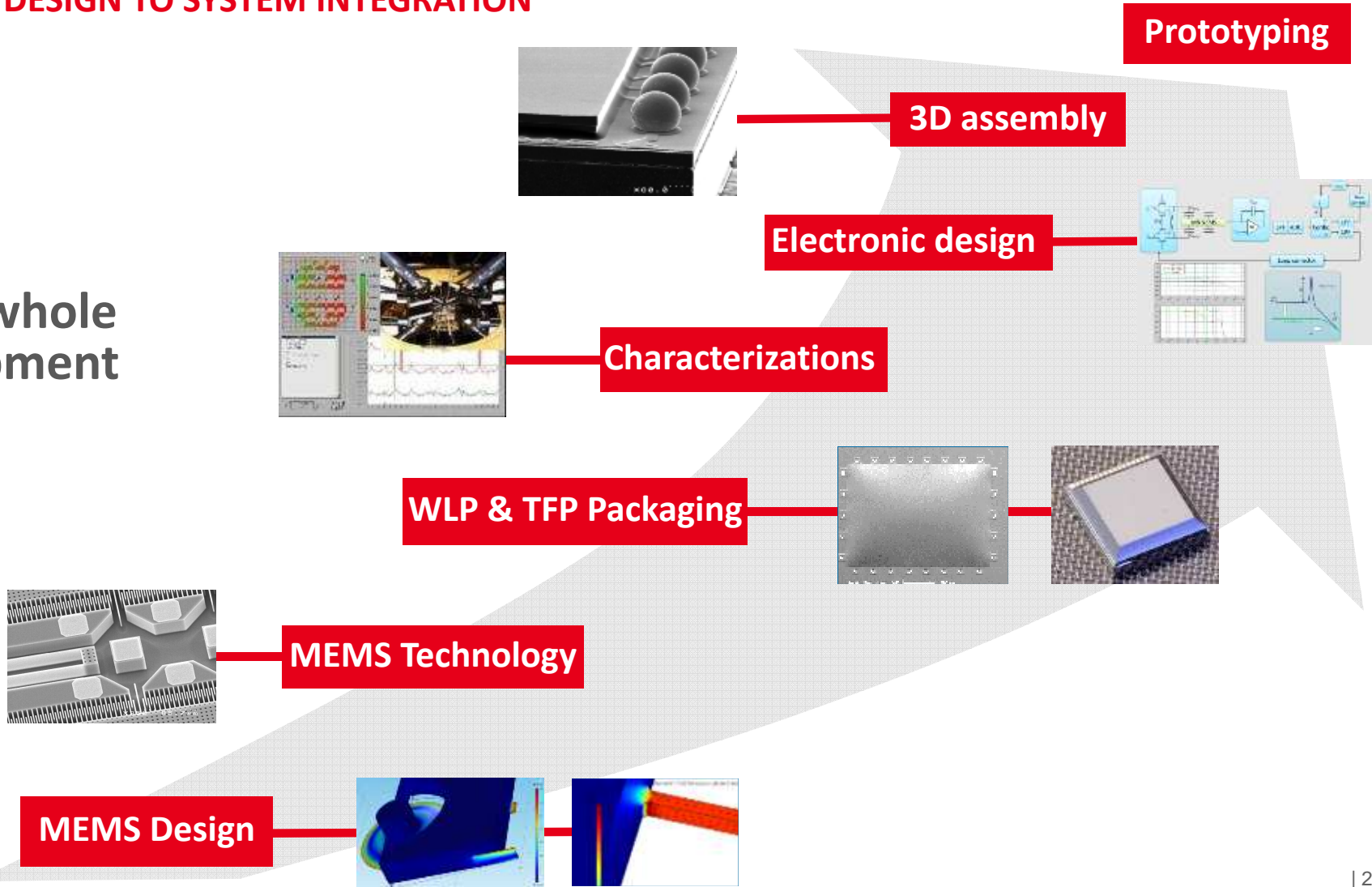


LETI MEMS ACTIVITIES OVERVIEW

Leti MEMS Workshop | June 20, 2017

A ONE-STOP MEMS R&D SOLUTION FROM MEMS DESIGN TO SYSTEM INTEGRATION

LETI covers the whole
chain of development



30+ YEARS BACKGROUND ON MEMS SENSORS

Key dates

1984

World 1st "Comb drive" accelero patent



1996

Spinoff



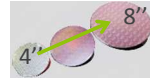
2007

Caltech Alliance on NEMS



2005

World 1st MEMS 200 cleanroom



2011

Spinoff



2011

Spinoff



2013

Spinoff



2015

World 1st 300mm MEMS wafer



2014

Startup



80s

90s

00s

10s

Industrial transfers

1980

Weight sensor

Terraillon



1981

Hygrometer



1987

Quartz accelero

THALES



1996

Geophone



Pressure



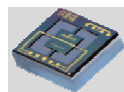
Accelero



1998

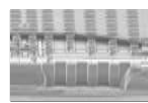
High perf. pressure

THALES



2005

Accelerometer



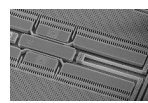
2008

TSV for imager



2011

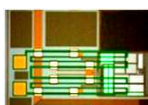
Inertial platform



2012

Above-IC GMR sensor

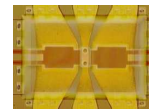
CONFIDENTIAL (US)



2013

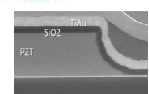
Thin Film pack.

CONFIDENTIAL (Ger)



2013

PZT Solgel



2013

300mm HD interposer

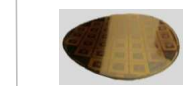
SHINKO



2013

100µm MEMS wafer thinning

CONFIDENTIAL (JP)



2014

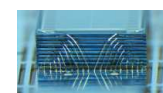
M&NEMS platform



2016

Capacitance stacking

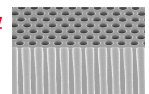
muRata



2017

Nanoporous capacitor

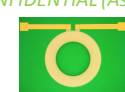
muRata



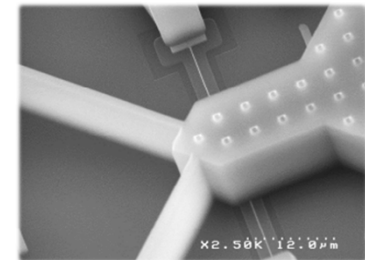
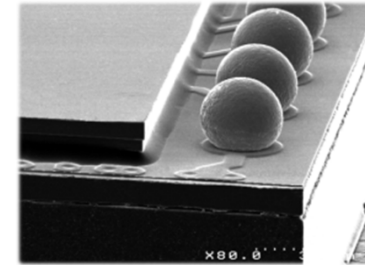
2017

PZT Solgel

CONFIDENTIAL (Asia)

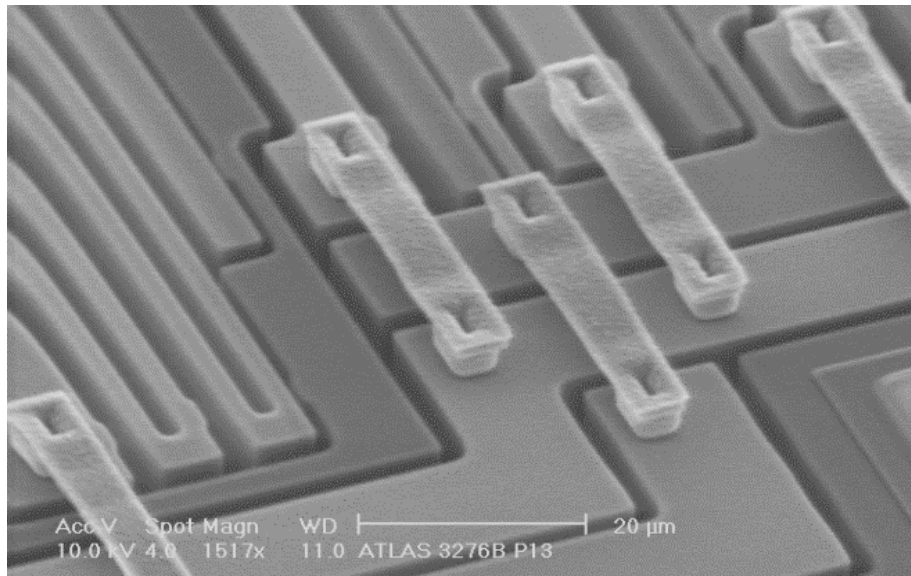


Highlights on Leti's MEMS realizations

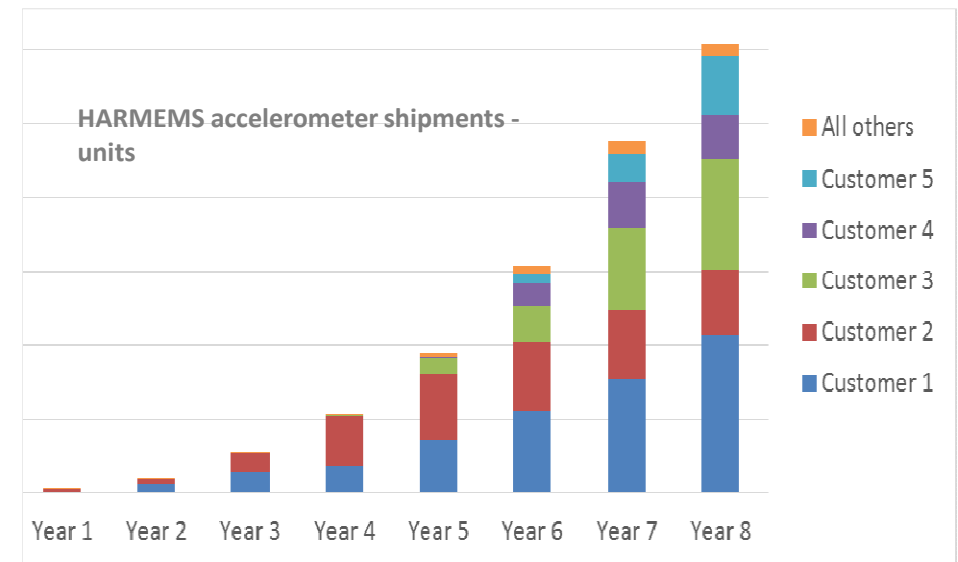


KEY ACCOMPLISHMENTS

Example of sensor technology transfer for the Automobile Market

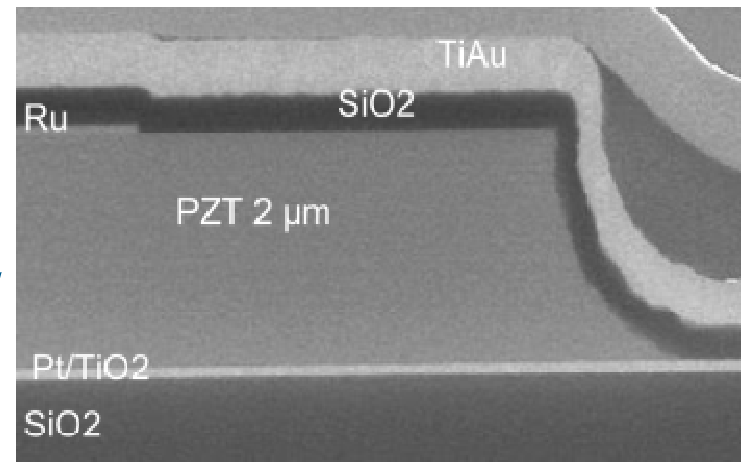
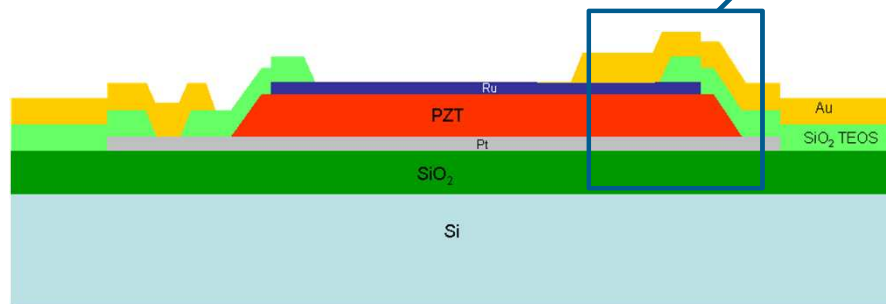


- Development and transfer of the HARMEMS technology to Freescale
- HARMEMS accelerometer shipments: **350+ million units**



KEY ACCOMPLISHMENTS

Example of technology transfer to industrial company



- Transfer to ST of a **Generic PZT stack** for MEMS sensors and actuators
- Now in production

KEY ACCOMPLISHMENTS

LETI ANNOUNCES THE WORLD'S FIRST 300mm MEMS WAFER (2015)

Demonstration done on M&NEMS accelerometers

- **70,000** 3-axis accelerometers per wafer

Moving to 300mm allows

- **Cost reduction** of at least 30% compare to a 200mm technology
- **Co-integration with advanced CMOS nodes** (.13 μ m and beyond)
- **Access to the existing 300mm TSV technology**



KEY ACCOMPLISHMENTS

LETI startups in Microsystems in last 5 years



Multi-gas analyzers coupling
gas chromatography and NEMS



Piezo-MEMS variable focus lens
for mobile phone camera



MEMS-based NDIR sensor
for air quality monitoring



Innovative piezoelectric
energy harvesting

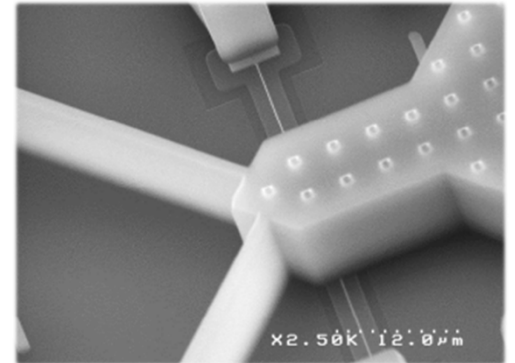
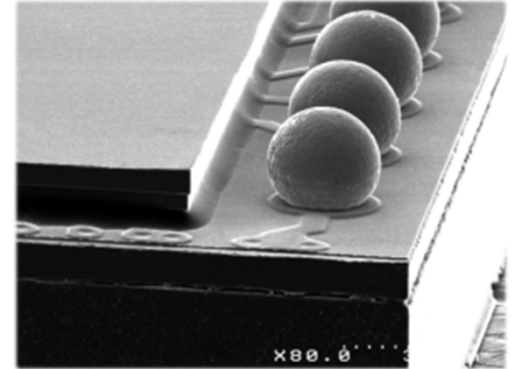


Integration of MEMS and
electronic devices into textiles



MEMS and QCL-based photo-
acoustic gas analyzer

Technological Differentiation M&NEMS Platform



MEMS ISSUES FOR NEW MARKETS

Issues

Strong cost pressure

- Miniaturization
- Process Sharing

Growing use of Combo sensors

MEMS components

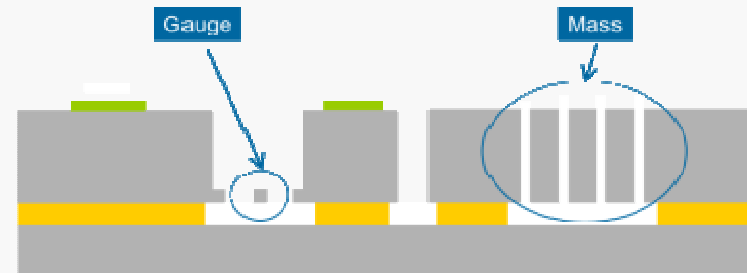
- Accelerometer
- Gyroscope
- Magnetometer
- Pressure sensor
- Microphone
- ...



LETI's Solution

Goal : "Generic", efficient and reliable MEMS platform

M&NEMS Platform

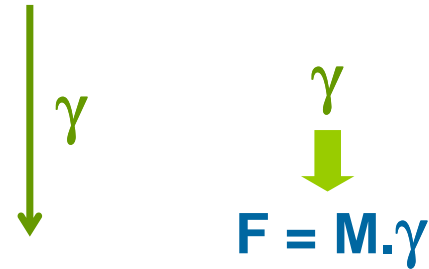
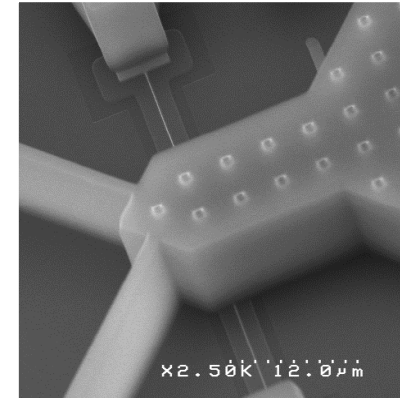
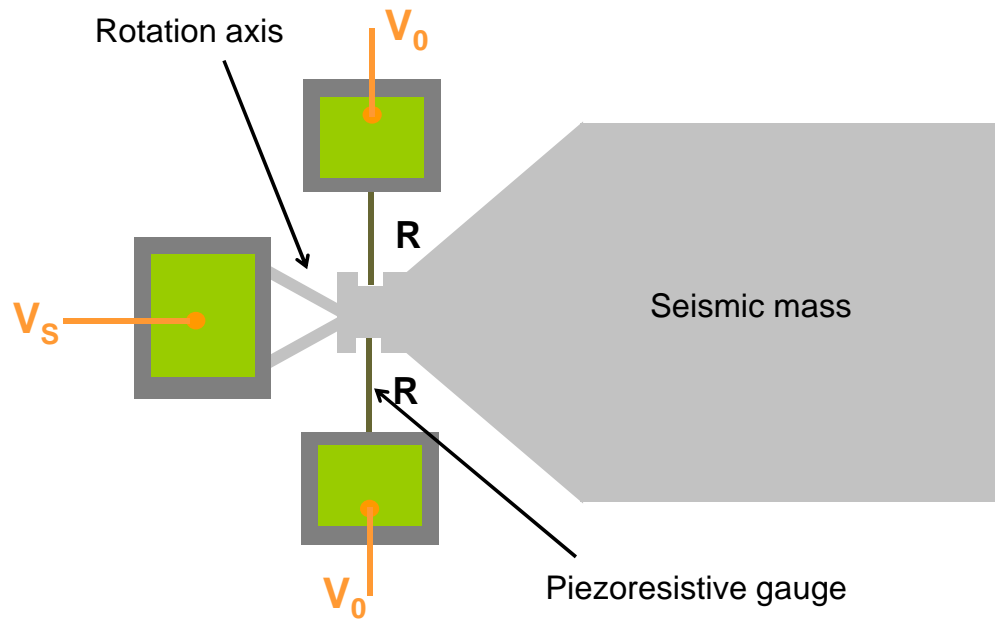


MEMS size mechanical part

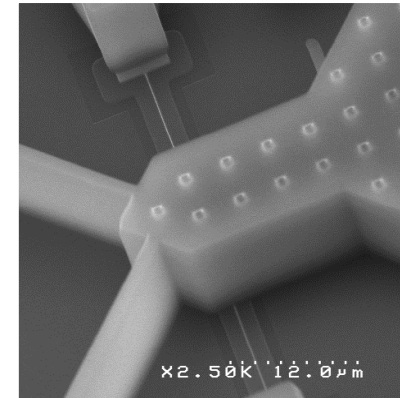
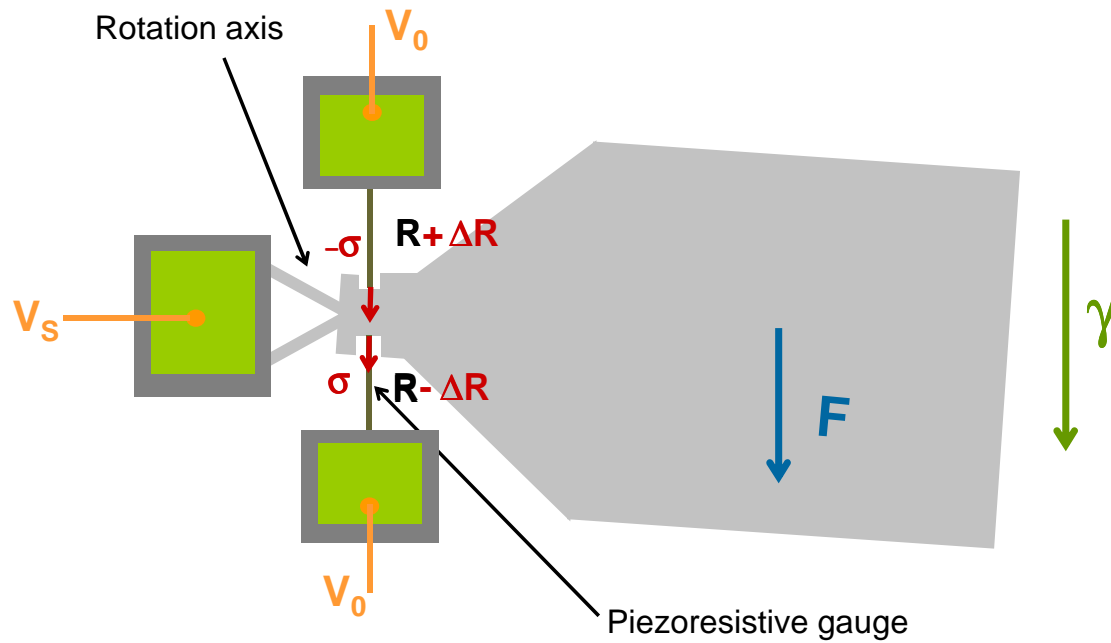
↑ Separate optimization ↓

Nano-size piezoresistive gauge

M&NEMS WORKING PRINCIPLE

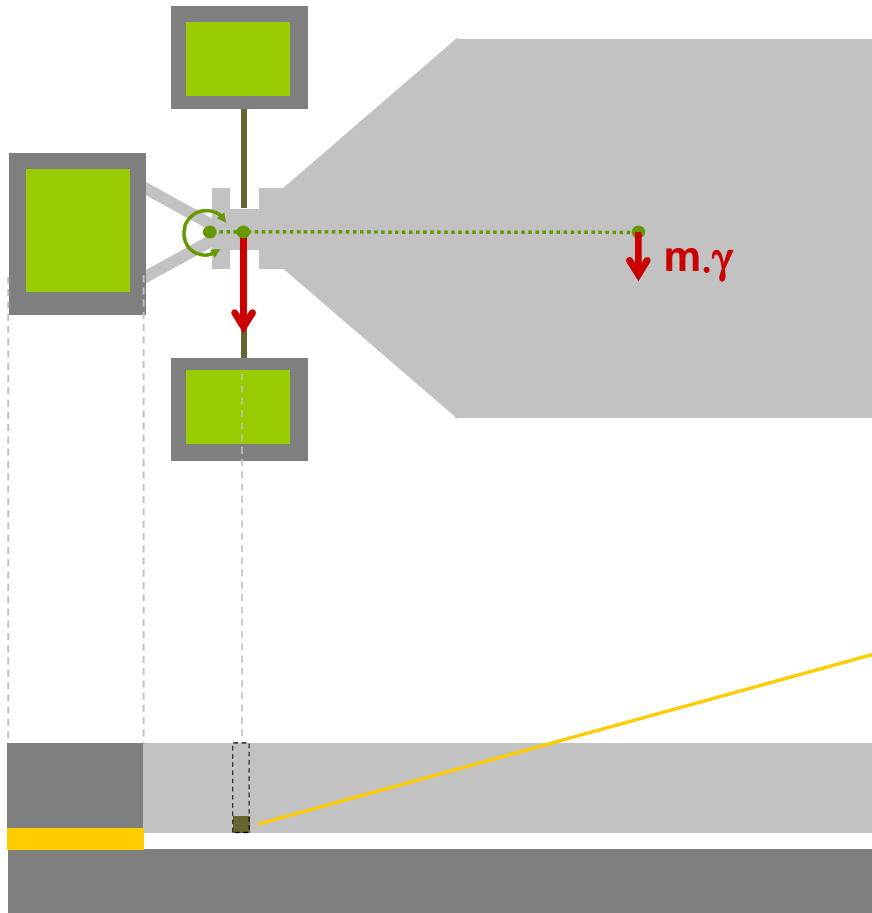


M&NEMS WORKING PRINCIPLE

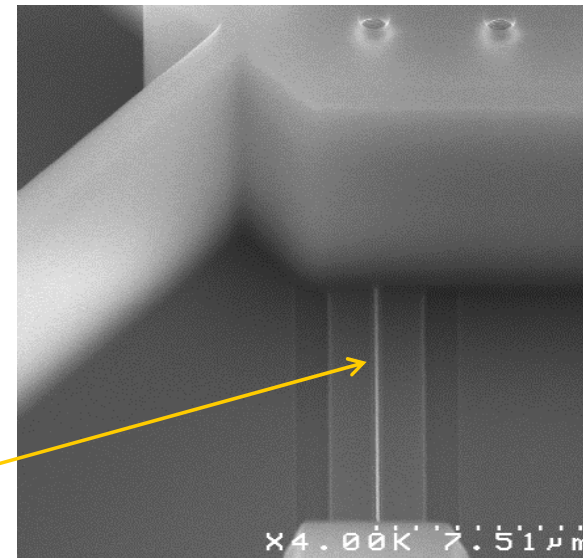


$$\begin{array}{c}
 \gamma \\
 \downarrow \\
 F = M \cdot \gamma \\
 \downarrow \\
 \sigma \\
 \downarrow \\
 \frac{\Delta R}{R} = \pi \sigma
 \end{array}$$

M&NEMS WORKING PRINCIPLE

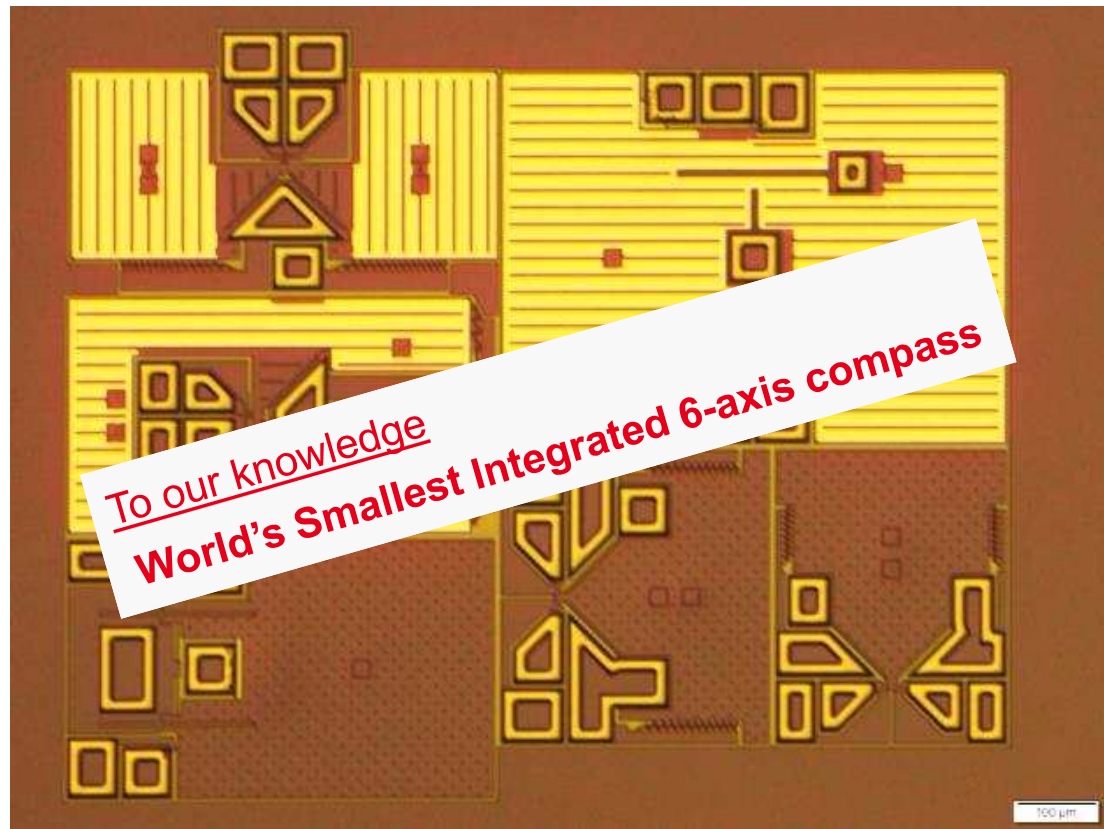


Design lever effect
Stress magnification : x30



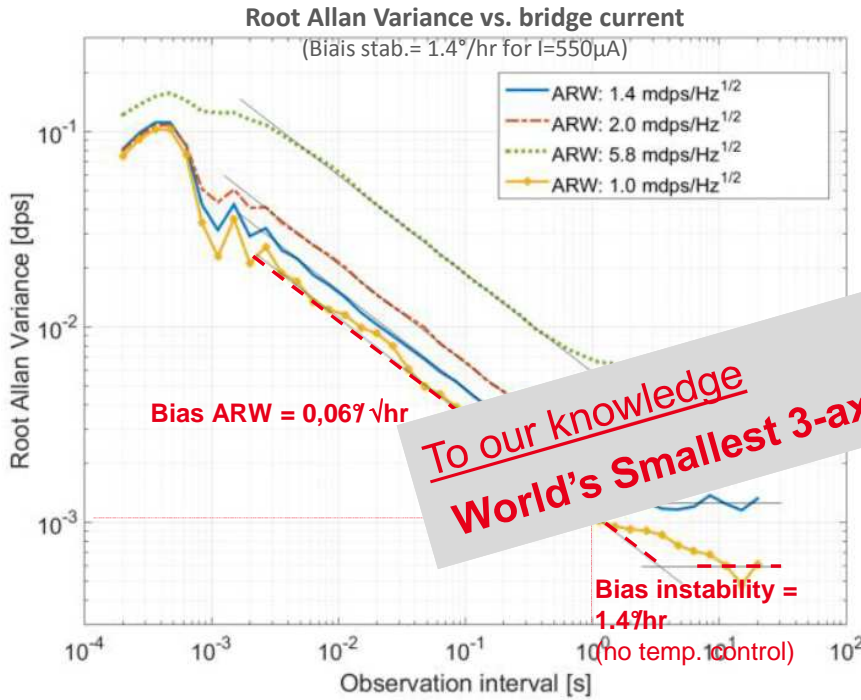
Influence of 2 different thicknesses
Stress magnification : x100

M&NEMS 6-AXIS COMPASS

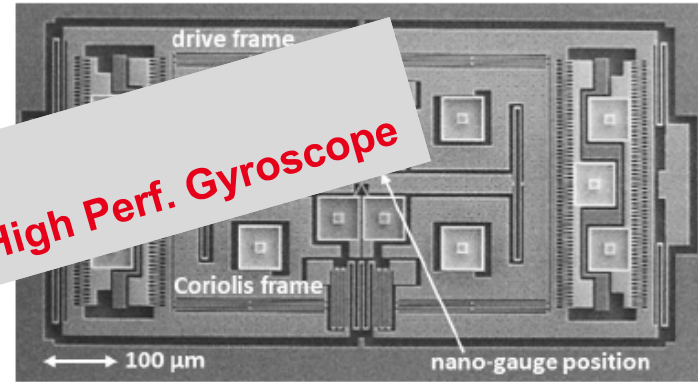


6-axis M&NEMS compass
(mechanical footprint $\approx 1,1\text{mm}^2$)

M&NEMS GYROSCOPE



**To our knowledge
World's Smallest 3-axis High Perf. Gyroscope**



Device area: 800µm x 450µm (0.36mm²)

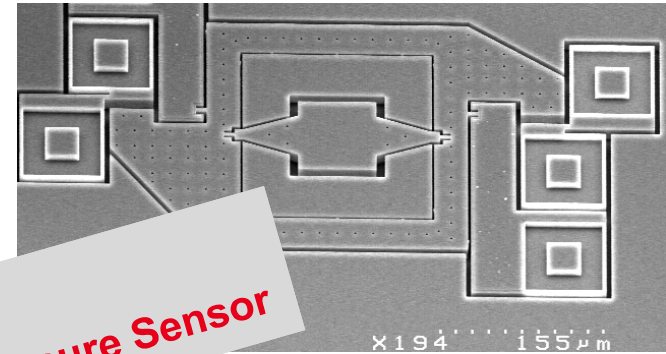
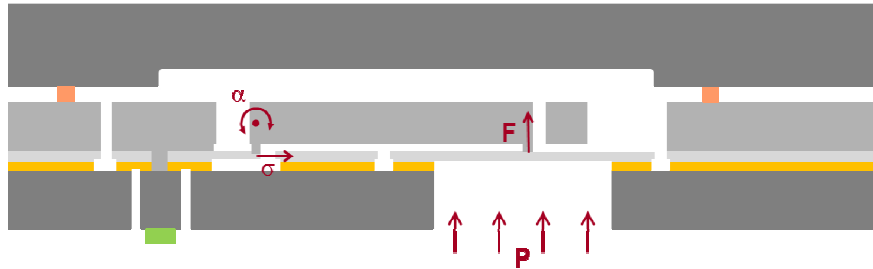
- Bias instability = 1.4°/hr
- 3-Axis Gyro in 2mm²
- Open-loop detection
- Q-factor : 3,000 (4 mbar WLP)



Possible further improvements by :

- Lowering package pressure (4 → < 1mbar)
- Increasing MEMS thickness (20 → 60µm)
- ...

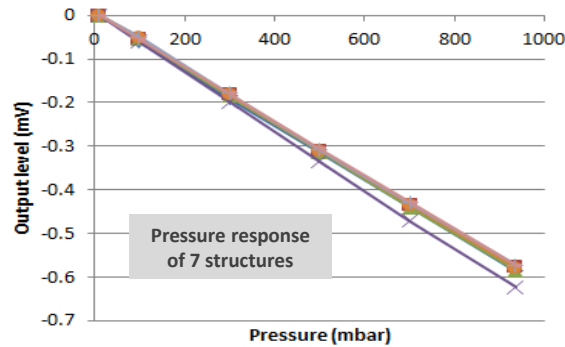
M&NEMS PRESSURE SENSOR



*To our knowledge
World's Smallest High Perf. Pressure Sensor*

First design (consumer)

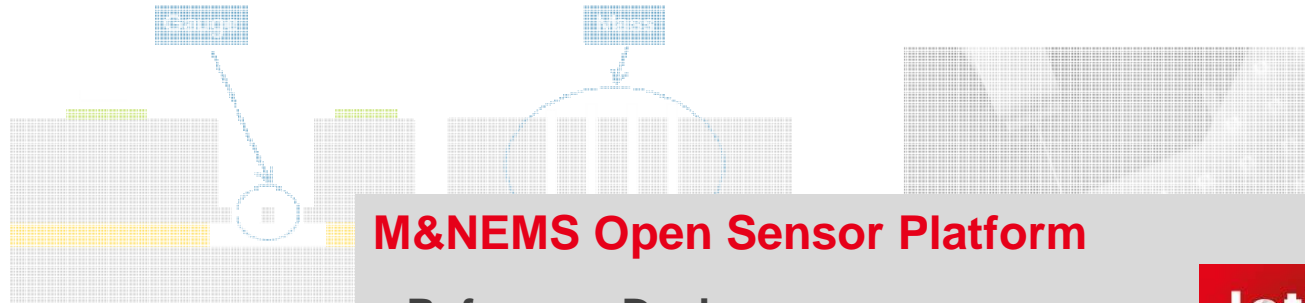
- Range : **> 1.4 bar**
- Resolution : **2 Pa**
- Die size : **0,45 mm²** (Mechanical footprint : 0,12mm²)
- Non-linearity **< 0.15% FS**



Main Interests

- Small footprint
- High linearity
- Reliability:
 - ✓ Protected gauge from external environment
 - ✓ Over-pressure protection (stops)
- Auto-test electrode
- 2 configurations: **Absolute / Differential**
- Co-integration with other sensors
- Compatible with high temperature application

M&NEMS: WORLD-FIRST MULTI-SENSORS PLATFORM

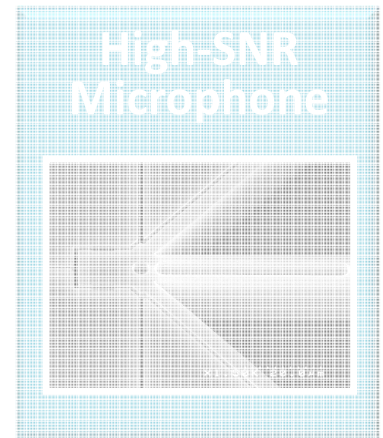
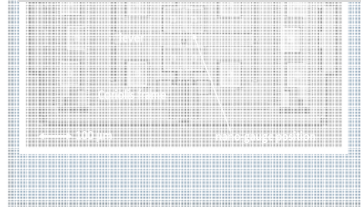


M&NEMS Open Sensor Platform

- **Reference Designs**
- **MEMS PDK** supported by
 - ✓ Ready-to-use design flow
 - ✓ Layout for physical verification
 - ✓ Models for ASIC co-simulation
- **Fabrication (MPW) and MEMS Characterization**

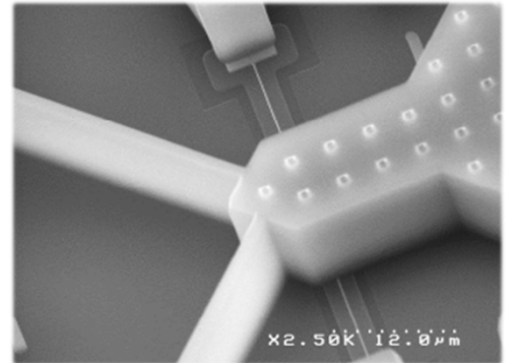
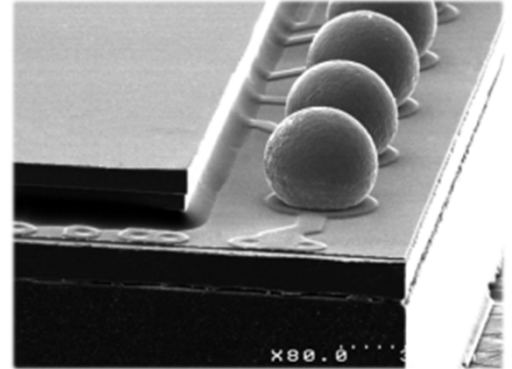


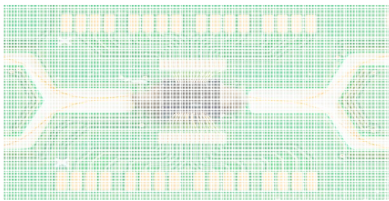
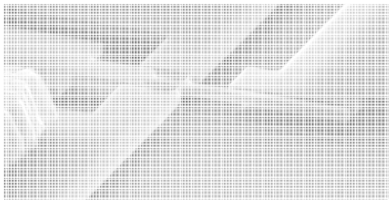
- **Innovative Approach**
(20+ patents)
- **Ultra-Miniaturized sensors**
(e.g.: 6-axis combo in 4mm²)
- **High performance**
(e.g.: 1.2°/h gyro instability)
- **Low power consumption**
(e.g.: 1mW 3-axis gyro)



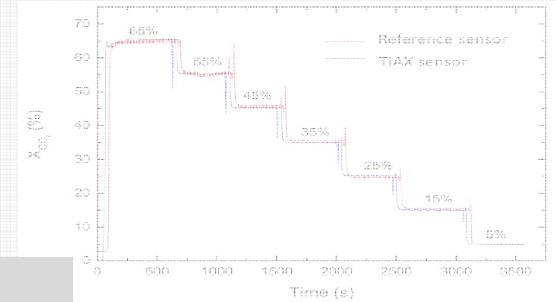
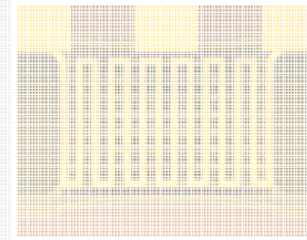
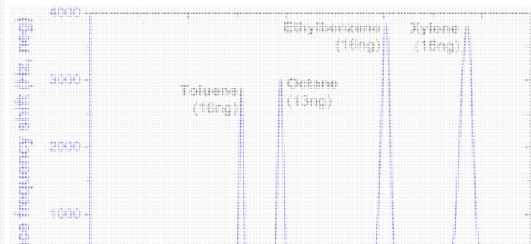
Technological Differentiation

Gas Sensors





MEMS-based sensor



MEMS-based Gas sensor

4 Technologies

- ✓ Gravimetric
- ✓ Infrared
- ✓ Photo-acoustic
- ✓ Thermo-Conductivity



3 Startups



Air Quality City Map



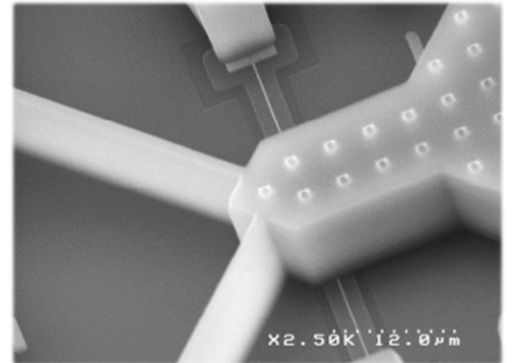
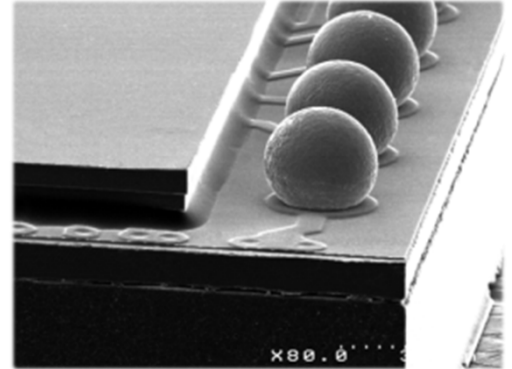
Photo-Acoustic sensor



- ✓ Range 100-300 ppm
- ✓ LOD 40 ppm @1000 ppm
- ✓ Max power up to 2 mW

NDIR based sensor

Technological Differentiation Piezoelectric material



PIEZOELECTRIC MATERIAL: STATE OF THE ART EXPERTISE

PZT

Technology

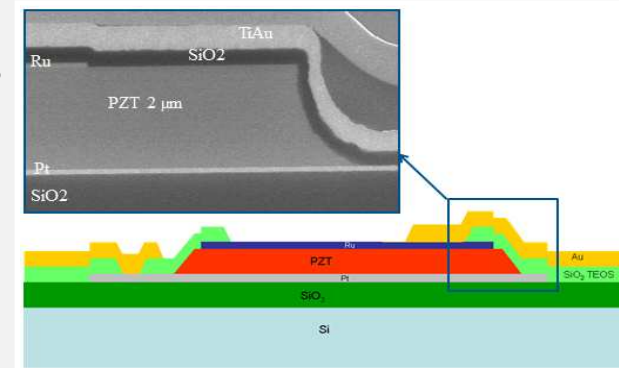
- ✓ Well mastered Solgel technology with **state of the art piezoelectric properties**
- ✓ A **complete 8" pilot line**: from PZT material to MEMS devices

Achievements

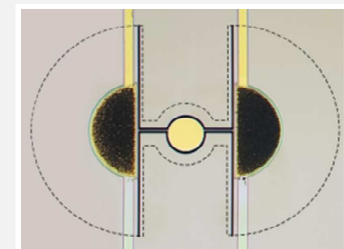
- ✓ Several PZT device demonstrations: **variable focus lens, micro-pump, optical scanner, haptic actuator...**
- ✓ **2 Technological Transfers** to  and to a **World-Class Foundry**

On-Going Developments

- ✓ Improvement of PZT actuator reliability and performances with doping
- ✓ PZT **dry etching** (In collaboration with tool supplier)
- ✓ **Lead-Free piezoelectric material development and integration**
- ✓ Investigation of emerging PZT-MEMS devices : Loudspeaker, Pyroelectric device for gas sensor...



Variable focus lens



Optical scanner

PIEZOELECTRIC MATERIAL: STATE OF THE ART EXPERTISE

AlN

Technology

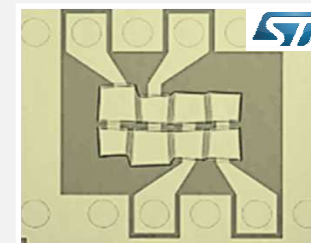
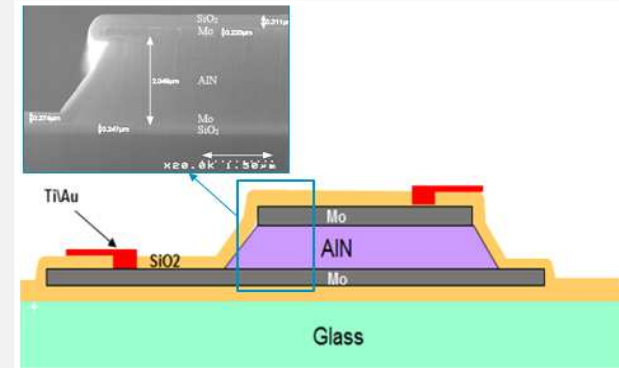
- ✓ 7 years of industrial development with ST ⇒ high maturity process, reliability, throughput...
- ✓ A complete 8" pilot line: from AlN material to MEMS devices

Achievements

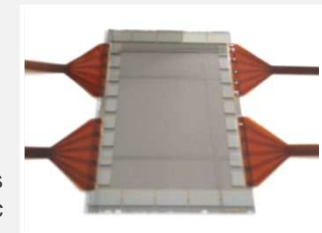
- ✓ Several AlN device demonstrations : **BAW filter**, **Haptic actuator** ...
- ✓ On-going Technological Transfer to a World-Class Foundry

On-Going Developments

- ✓ For RF devices : Lamb waves filter...
- ✓ For sensors: **High-SNR Microphone**, **Pyrometer** for gas sensor
- ✓ For actuators: **pMUT**
- ✓ **Transparent piezoelectric actuator** for haptics...



BAW filter



AlN-on-glass
for haptic

**Thank you for
your attention**



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